### **1.27MM PITCH SLIM-GRID<sup>®</sup> UNSHROUDED HEADERS (BOARD TO BOARD)**

### 1.0 SCOPE

This Product Specification covers the <u>1.27</u>mm centerline (pitch) printed circuit board (PCB) connector series

### 2.0 PRODUCT DESCRIPTION

### 2.1 PRODUCT NAME AND SERIES NUMBER(S)

### Product Name

1.27mm Pitch SLIM-GRID<sup>®</sup> Unshrouded Headers

Series Number 87933



### 2.2 DIMENSIONS, MATERIALS, PLATINGS AND MARKINGS

See Sales Drawings, SD-87933-0001, SD-87933-014, SD-87933-100 and SD-87933-101 for information on dimensions, materials, plating, and markings.

### 2.3 SAFETY AGENCY APPROVALS

UL FILE NUMBER : File E29179, Vol 10 CSA File Number : 152514 (LR 19980)



CSA approval meets following standards/test procedures: a) CSA std. C22.2 No. 182.3-M1987 b) UL-1977

\* "C" and "US" mark adjacent to CSA signifies that the product has been evaluated to the applicable CSA and ANSI/UL standards, for use in Canada and US respectively. Series 78120, 87933, 200989, 201021, 201022, 201173, rated 4.3A, 125Vac

REVISION:					SHEET No.
A2	<u>EC No:</u> 118480 DATE: 2017/06/22	1.27MM PITCH SLIM-GRID <sup>®</sup> UNSHROUDED HEADERS		<b>1</b> of <b>9</b>	
DOCUMENT NUMBER:		CREATED / REVISED BY: <u>CHECKED BY:</u> <u>APPRO</u>		/ED BY:	
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### 3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

The following documents form a part of this specification to the extended specified herewith. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence.

### Reference Product Specifications

781200001 1.27mm Pitch SLIM-GRID<sup>®</sup> Vertical SMT Receptacle

### 4.0 RATINGS

### 4.1 MAXIMUM VOLTAGE

<u>125</u> Vac

### 4.2 MAXIMUM CURRENT

4.3 Amps per Pole (only 1 contact powered up)

Current rating is application dependent and each application should be evaluated by the end user for compliance to specific safety agency requirements. The ratings listed in the chart below are per Molex test method based on a 30° C maximum temperature rise over ambient temperature and are provided as a guideline. Appropriate derating is required based on circuit size, ambient temperature, copper trace size on the PCB, gross heating from adjacent modules/components and other factors that influence connector performance.

		CIRCUIT SIZE										
	2*	4	6*	8*	10*	12*	14	16*	18*	20*	22*	24
Curren t Rating (Amps , Max)	3.60	3.00	2.70	2.50	2.40	2.30	2.20	2.10	2.10	2.00	2.00	1.90



\*Extrapolated from test data. Refer below for more information.

### 4.3 TEMPERATURE

Operating:  $-55^{\circ}C$  to  $+105^{\circ}C$ Non-operating:  $-55^{\circ}C$  to  $+105^{\circ}C$ 

### 5.0 PERFORMANCE

### 5.1 ELECTRICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
1	Contact Resistance (LLCR)	Mate connectors: apply a maximum voltage of <b>20</b> mV and a current of <b>100</b> mA. (EIA-364-23) Note: Wire resistance and traces shall be removed from the measured value.	<b>30</b> milliohms [MAXIMUM] [initial]
2	Insulation Resistance	Mated & unmount connectors: apply a voltage of <b>500</b> VDC between adjacent terminals and between terminals to ground. (EIA-364-21)	<b>1000</b> Megohms [MINIMUM]
3	Dielectric Withstanding Voltage	Mated & unmount connectors: apply a voltage of <b>1000</b> VAC for <b>1</b> minute between adjacent terminals and between terminals to ground. Unmate & unmount connectors: apply a voltage of <b>1250</b> VAC for <b>1</b> minute between adjacent terminals and between terminals to ground. (EIA-364-20)	No breakdown; Current leakage < <b>5</b> mA
4	Temperature Rise	Mate connectors: measure the temperature rise of the contact when the maximum DC rated current is passed. (EIA-364-70, Method 1)	Temperature rise: <b>+30</b> °C [MAXIMUM]

	5.2	MECHANICAL REQUIR	EMENTS			
	<b>REVISION:</b>	ECR/ECN INFORMATION:	TITLE: PROI	PRODUCT SPECIFICATION 1.27MM PITCH SLIM-GRID <sup>®</sup>		SHEET No.
	A2	<u>EC No:</u> 118480	_			<b>3</b> of <b>9</b>
	AZ	<u>DATE:</u> 2017/06/22	UNSHROUDED HEADERS			303
ĺ	DOCUMEN	T NUMBER:	CREATED / REVISED BY: CHECKED BY:		<u>APPROV</u>	ED BY:
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ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
5	Connector Mate & Unmate Force	Mate and unmate connectors at a rate of <b>25.4 mm/min</b> (EIA-364-13D, Method A)	Mate Force 15N (24ckt) 10N (4ckt) [MAXIMUM] Unmate Force 3.0N (24ckt) 0.5N (4ckt) [MINIMUM]
6	Durability	Mate connectors up to <b>50</b> cycles at a maximum rate of <b>500 ±50 cycles/hr</b> . (EIA-364-09)	Appearance: No Damage Contact Resistance: <b>15</b> milliΩ [MAXIMUM] [CHANGE FROM INITIAL]
7	Reseating	Manually mate and unmate the connector with mating half for <b>3 cycles</b> with rate of <b>5</b> <b>cycles/min</b> maximum. (EIA-364-09)	Appearance: No Damage Contact Resistance: <b>15</b> milliΩ [MAXIMUM] [CHANGE FROM INITIAL]
8	Terminal Retention Force (in Housing)	Axial pullout force on the terminal in the housing at a rate of $25 \pm 6$ mm ( $1 \pm \frac{1}{4}$ inch) per minute. (EIA-364-29, Method C)	<b>4.0 N</b> [MINIMUN]
9	Vibration	Mate connectors and subject to the following vibration conditions, for a period of <b>2 hours</b> in each 3 mutually perpendicular axis. Amplitude: <b>1.52mm</b> (.060 inch) peak to peak Test pulse: <b>half sine</b> Sweep: <b>10-&gt;55-&gt;10 Hz</b> in <b>1 minute</b> Duration: <b>2 hours</b> in each x-y-z axis. (EIA-364-28, Test Condition I)	Appearance: No Damage <b>15</b> milliohms [MAXIMUM] (change from initial) Discontinuity: <b>1.0 µs</b> [maximum]

REVISION:	ECR/ECN INFORMATION:	TITLE: PROI	DUCT SPECIFICATION		SHEET No.	
A2	<u>EC No:</u> 118480	1.27MM PITCH SLIM-GRID <sup>®</sup>			<b>4</b> of <b>9</b>	
	DATE: 2017/06/22	UNS	UNSHROUDED HEADERS			
DOCUMEN	T NUMBER:	CREATED / REVISED BY: CHECKED BY: APPRO		/ED BY:		
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10	Mechanical shock	Mate connectors and su following shock conditio be applied along 3 mutu axis. (total of 18 shocks Peak value: <b>490</b> m/s sq Test pulse : <b>half sine</b> Duration : <b>11 ms</b> in eac (EIA-364-27B Condition	ns, 3 shocks shall ually perpendicular ) . (50G) h x-y-z axis	Appearance: No Damage Contact Resistance: <b>15</b> milliΩ [MAXIMUM] [CHANGE FROM INITIAL] Discontinuity: <b>1.0 μs</b> [maximum]
1'	Thermal shock	Mate connectors, expose to 5 cycles of:-Temperature °cDuration (minutes)-55+0/-530Transfer time from cold to hot5 maximum+105+3/-030Transfer time from hot to cold5 maximum(EIA-364-32G Method A, Condition VII)		Appearance: No Damage Contact Resistance: <b>15</b> milliΩ [MAXIMUM] [CHANGE FROM INITIAL]
12	Temperature lifeMate connectors, expose to:-Temperature: 105 ± 2 °c Duration: 96 hours.(EIA-364-17, Method A, Condition 4)		Appearance: No Damage Contact Resistance: <b>15</b> milliΩ [MAXIMUM] [CHANGE FROM INITIAL]	

REVISION:	ECR/ECN INFORMATION:	TITLE: PRODUCT SPECIFICATION			SHEET No.
A2	<u>EC No:</u> 118480		1.27MM PITCH SLIM-GRID <sup>®</sup>		
AZ	<u>DATE:</u> 2017/06/22	UNS	<b>5</b> of <b>9</b>		
DOCUMENT	<u> NUMBER:</u>	CREATED / REVISED BY: <u>CHECKED BY:</u> <u>APP</u>		<u>APPROV</u>	/ED BY:
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# **molex**<sup>®</sup> PRODUCT SPECIFICATION

			Mate connector and expose to	D:-	Appearan	ce: No Damag	je
	13	Cyclic temperature and humidity	Temperature: $25 \pm 3$ °C @ Humidity: $80\% \pm 3\%$ And Temperature: $65 \pm 3$ °C @ Humidity: $50\% \pm 3\%$ Ramp times should be 0.5 ho		1 [M/ [CHANGE Dielectri	t Resistance: 5milliΩ AXIMUM] FROM INITIA c withstanding	-
			and dwell times should be 1.0 Dwell times start when the temperature and humidity hav stabilized within the specified Duration: <b>24 cycles (72 hour</b> )	/e levels.	No t Insulatio	′oltage: preakdown on resistance: egaΩ minimum	1
			Mate connectors and expose	to:	Appearan	ce: No Damag	je
	14	Low temperature test	Temperature: <b>-40 ± 3</b> °C Duration: <b>96 +5/-0</b> hours			t Resistance: <b>5</b> milliΩ	
			(EIA-364-59A)		-	AXIMUM] FROM INITIA	L]
			Mate connectors and expose	to:		ce: No Damag	je
	15	SO <sub>2</sub> gas (gold plated only)	SO <sub>2</sub> gas density: <b>50 ±5</b> ppm Temperature: <b>40 ±2</b> °C Duration: <b>24 hours</b> Humidity: <b>60-75%.</b>		Contact Resistance: <b>15</b> milliΩ [MAXIMUM] [CHANGE FROM INITIAL]		L]
	16	Salt spray	following salt mist condition: Concentration : $5 \pm 1\%$ Temperature : $35 \pm 1/-2$ °C Test time : <b>48 hours</b> (note: immediately after expositest specimens shall be dippedippedippedippedippedippedippedip	Concentration : $5 \pm 1\%$ Temperature : $35 \pm 1/-2$ °C Test time : $48$ hours (note: immediately after exposure, the test specimens shall be dipped in running tap ( $\leq 38$ °C) for 5 mins max and dried for 16 hour max in a circulating air oven at 38 $\pm 3$ °C. Sample examination done in room		t Resistance: <b>5</b> milliΩ AXIMUM]	
			(EIA-364-26C, Condition B)				
REVIS	ION:	ECR/ECN INFORMATION					SHEET No.
A	2	<u>EC No:</u> 118480					<b>6</b> of <b>9</b>
		DATE: 2017/06/22		HROUDED			
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17	Solderability	Unmate connector. Steam age for <b>8 hour ± 15 min.</b> (precondition: Condition C) <u>SMT</u> Surface mount process simulation test Solder paste is deposited onto screen (e.g.ceramic plate) via stencil. The connectors are placed onto the solder paste print. Subject the substrate and component to the reflow process through a convection oven. Refer to section 8.0 for temperature profile. Flux type: <b>ROL0</b>	95% of the immersed area must show no voids, pin holes
18	Resistance to solder Heats	SMT Convection reflow Sample to be passed through reflow over according to temperature profiles (shown in section 8.0) (EIA-364-56C, Procedure 6)	Appearance: no damage

#### 6.0 PACKAGING

Parts shall be packaged to protect against damage during handling, transit and storage. Refer to Packaging Specification, PK-87933-565 AND PK-87933-300

### 7.0 OTHERS

Although some discolouration could be seen on the soldertail after reflow, it does not impact on the product's performance.

REVISION: A2	ECR/ECN INFORMATION: EC No: <b>118480</b> DATE: <b>2017/06/22</b>	TITLE: PRODUCT SPECIFICATION 1.27MM PITCH SLIM-GRID <sup>®</sup> UNSHROUDED HEADERS		<u>SHEET No.</u> <b>7</b> of <b>9</b>	
DOCUMEN	T NUMBER:	CREATED / REVISED BY: <u>CHECKED BY:</u> <u>APPRO</u>		/ED BY:	
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TEMPLATE FILENAME: PRODUCT_SPEC[SIZE_A](V.2).DOC					

### **8.0 TEST SEQUENCES**

Sequential Tests Group ->	1	2	3	4	5	6	7	8	9	10	11
Test or Examination $oldsymbol{\Psi}$											
Sample size	5	5	5	5	5	5	5	5	5	5	5
Resistance to Soldering Conditions	1	1	1	1	1	1	1	1			
Low Level Contact Resistance (LLCR)	2, 5, 7	2, 5, 7, 9	2, 5, 7, 9		2, 4	2, 4	2, 4	3, 7			
Insulation Resistance				2, 6							
Dielectric Withstanding Voltage				3, 7							
Connector Mate								2, 6			
Connector Unmate								4, 8			
Durability	3(a)	3(a)	3(a)					5			
Reseating	6	8									
Vibration			6								
Mechanical Shock			8								
Thermal Shock		4		4							
Temperature Life	4		4(a)								
Cyclic Temperature & Humidity		6		5							
Low Temperature Test					3						
SO <sub>2</sub> gas (Gold plated)						3					
Salt Spray							3				
Pin Retention (in housing)									1		
Solderability										1	
Temperature Rise											1

REVISION: A2	ECR/ECN INFORMATION: EC No: <b>118480</b> DATE: <b>2017/06/22</b>	TITLE: PROI 1.27M UNS	<u>SHEET No.</u> 8 of 9		
DOCUMENT NUMBER:		CREATED / REVISED BY:	CHECKED BY:	APPROVED BY:	
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